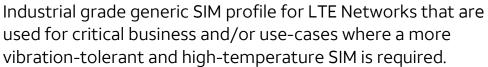


Industrial Grade SIM Datasheet





Description

Features

- Designed for Industrial grade applications
- Extended Life span
- Subscription Management Capable: No
- AT&T UICC Version: UICC-G
- Volte

Technical Specifications

Support Voltage	Class A, B, C
Grade	Industrial
Operating Temperature	-40°C + 105°C
Storage Temperature	-40°C + 105°C
Data Retention	10 Years
Network	Jasper
IMSI Range	310-170
Subscription Management Version	N/A



Orderable Part Numbers

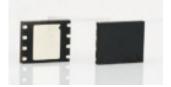
Product Name	IOT_UICC-G_V070_2FF_IND
Plug-in Type	2FF
Dimensions	25,0 x 15,0 mm x 0.76mm
SKU	G0702
UPC	207376007019
Chip Manuf.	Infineon
Chip Reference	SLM76CF3601P
SIM Vendor	Gemalto



Product Name	IOT_UICC-G_V070_3FF_IND
Plug-in Type	3FF
Dimensions	15,0 x 12,0 mm x 0.76mm
SKU	G0703
UPC	207376007026
Chip Manuf.	Infineon
Chip Reference	SLM76CF3601P
SIM Vendor	Gemalto



Product Name	IOT_UICC-G_V070_MFF2_IND
Plug-in Type	MFF2
Dimensions	6,0 x 5,0 mm x 0.82mm
SKU	G0705
UPC	207376007033
Chip Manuf.	Infineon
Chip Reference	SLM76CF3601P
SIM Vendor	Gemalto



Compliance

The SIM profiles are compliant with the following standards:

- Cards with contacts
 - Physical characteristics: ISO/IEC 7816-1
 - Dimensions and location of the contacts: ISO/IEC 7816-2
 - Electrical interface and transmission protocols: **ISO/IEC 7816-3**
 - Organization, security and commands for interchange: ISO/IEC 7816-4
- UICC Physical and logical characteristics: 3GPP TS 31.101 release 8
- USIM Application: 3GPP 31.102 release 8
- ISIM Application: 3GPP 31.103 release 8



Disclaimers

AT&T Product Advisory Notice on the Use of Industrial Grade SIM versus Consumer Grade SIM Please be advised of a critical difference between Consumer grade SIMs and Industrial grade SIMs:

- Consumer grade SIMs have a lower MTBF (mean time before failure) and are to be used in stable, non-critical consumer devices where they are easily accessed and swapped when needed.
- Industrial grade SIMs are used for critical business and sometimes automotive use-cases where a more vibration-tolerant and high-temperature SIM is required.

Plug-in Form Factors:

- Cards should not be submitted to thermal shock.
- Cards should not be on contact with silicone rubber material.
- Cards should not be submitted to rapid modification of temperature and humidity (maximum 5°c/minute) and/or humidity, to avoid condensation on the card surface.